

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A process, comprising:

 performing certain process steps from the top side of a substrate carrying a plurality of devices, at least certain of the devices having a micro-machined mesh;

 attaching a carrier wafer to the top of the substrate;

 reducing the thickness of the substrate; ~~and~~

 continuing the process of fabricating the plurality of devices from the back side of the substrate;

and

releasing said micro-machined meshes.

2.(original) The process of claim 1 wherein said performing includes forming and patterning a layer of resist.

3. (original) The process of claim 1 wherein said performing includes forming a plurality of meshes.

4. (original) The process of claim 1 wherein said continuing includes forming vent holes.

5. (currently amended) The process of claim 4 additionally comprising attaching a carrier wafer to the back side of the substrate and removing the carrier wafer from the top side of the substrate, ~~said process additionally comprising forming and releasing a plurality of meshes said releasing of said micro-machined mesh being performed~~ from the top side of the substrate.

6. (original) The process of claim 5 additionally comprising singulating the plurality of devices.

7. (original) A process, comprising:

 attaching a carrier wafer to a top side of a substrate carrying a plurality of devices, at least certain of said devices including a mesh;

 reducing the thickness of said substrate;

 performing process steps from the back side of said substrate;

 attaching a carrier wafer to the back side of said substrate and removing said carrier wafer from the top side of said substrate; and

 performing process steps from the top side of said substrate.

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8. (original) The process of claim 7 wherein said performing process steps from the back side of the substrate includes forming vent holes.
9. (original) The process of claim 7 wherein said performing process steps from the top side of said substrate includes forming and releasing a plurality of meshes.
10. (original) The process of claim 9 additionally comprising singulating the plurality of devices.
11. (currently amended) In a process for fabricating a MEMS device, the improvement comprising:
 - reducing the thickness of a substrate; and
 - attaching a carrier wafer to one of the top side and back side of the substrate for use during at least a part of the process of fabricating the MEMS device, said process including releasing at least one micro-machined mesh.
12. (original) In a process for fabricating a MEMS device, the improvement comprising:
 - reducing the thickness of a substrate carrying a plurality of devices;
 - using a carrier wafer attached to the top side of said substrate while at least certain process steps are performed from the back side; and
 - using a carrier wafer attached to the back side of said substrate while at least certain process steps are performed from the top side.